BGA Heat Sink - High Performance maxiFLOW w/Thermal Tape





ATS Part#: **ATS-52300P-C1-R0**

Description: 30.00 x 30.00 x 17.50 mm BGA Heat Sink - High Performance maxiFLOW w/Thermal

Tape

Heat Sink Type: maxiFLOW
Heat Sink Attachment: Thermal Tape

Equivalent Part Number: ATS-52300P-C2-R0

*Image above is for illustration purpose only.

Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- · Fabricated from extruded aluminum, which minimizes thermal resistance from the base to the fins, reduces weight and keeps costs low
- · Higher performance helps ensure reliable product life at a lower cost than other extruded heat sinks

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.4 °C/W	2.8 °C/W	2.4 °C/W	2.2 °C/W	2 °C/W	1.9 °C/W	1.7 °C/W
	Ducted Flow	2.7	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image Dimension A		Dimension B	Dimension C	Dimension D	TIM	Finish
	30.00 mm	30.00 mm	17.50 mm	53.34 mm	T412	BLUE-ANODIZED
B A	 Dimensior ATS-5230 (Saint-Gol Thermal p application ATS reser performan ATS certif 	to the example of the	eight from the bottor act heat sink assemb a provided for referent ate or change its pro-	m of the base to the oly with an equivalent only. Actual performance only. Actual performance without notice -6 and REACH comple.	t thermal ormance	interface material may vary by
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